AN11257 SPI secondary boot loader Rev. 1 — 10 September 2012

Application note

Document information

Info	Content
Keywords	LPC11xx, LPC17xx, SBL, SPI
Abstract	This application note describes how to implement a Secondary Boot Loader (SBL) using SPI Communication.



SPI secondary boot loader

Revision history

Rev	Date	Description
1	20120910	Initial version.

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SPI secondary boot loader

1. Introduction

This document describes the functional requirement specifications, implementation and usage of the SPI Secondary Boot Loader (SBL) on LPC11xx and LPC17xx family.

1.1 Project overview

This project can run on the LPC11xx and LPC17xx MCUs. In these MCUs, the primary boot loader resides in the boot block. The boot loader is executed every time the part is powered on or reset. It can execute the ISP command handler or the user application code, which is stored in sector 0 of internal flash memory.

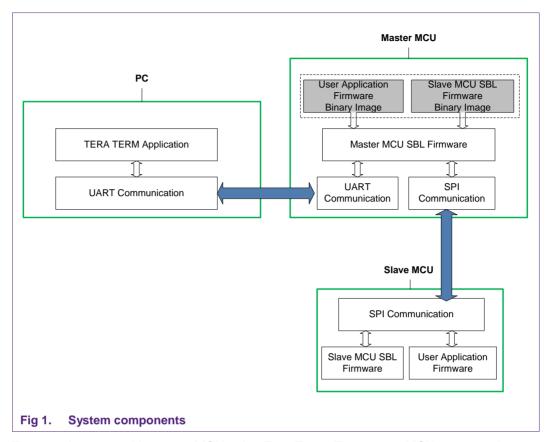
The SBL in this project refers to a user-defined application that provides the user with an option to update the User Application Firmware or execute the previously programmed User Application Firmware. It is placed from the address 0x00 so that when the primary boot loader runs user application, it executes first.

1.2 System components

The system components are shown in Fig 1.

UART communication between the PC and the master MCU is added to give user control over the firmware upgrade process.

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The user interacts with master MCU using Tera Term. The master MCU supports three commands: Read User Application Firmware ID from slave MCU, Upgrade User Application Firmware, and Upgrade SBL Firmware for slave MCU. Firmware data is stored in flash memory of master MCU, from sector 1 to the last sector.

Once the master MCU receives a command, it communicates to the slave MCU to perform the relevant actions. All transmissions between master MCU and slave MCU are done using SPI. The protocol in this case is covered in section 3.

Slave MCU has an SBL located at sector 0 of the flash memory. At startup, SBL validates user code by checking the firmware version ID (the last 4 bytes of flash memory). If the ID is invalid (0xFF), the slave MCU enters SBL mode and waits for new firmware over the SPI bus. If not, the MCU enters Application mode and executes the Reset Handler of User Application Firmware at address 0x1004.

In Application Mode, the slave also supports functions to read its User Application firmware version ID and upgrade the User Application firmware. Moreover, the firmware of SBL can also be upgraded. Using a special command, the user can ask the master MCU to communicate to the slave MCU in order to perform this function.

1.3 SPI communication

SPI is a full duplex serial interface. Device communicates using master/slave relationships, in which the master initiates the data frame. When the master generates a clock and selects a slave device, data are transferred in both directions. It is up to the master and slave devices to know whether a received byte is meaningful or not.

In this project, the slave MCU will send a READY byte (0xAA) on SPI bus once it enters idle state. The master MCU must read this byte before sending any function to Slave.

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A pair of parameters called clock polarity (CPOL) and clock phase (CPHA) determines the edges of the clock signal on which the data are driven and sampled. Each of the two parameters has two possible states, which allows for four possible combinations, all of which are incompatible with one another. So a master/slave pair must use the same parameter pair values to communicate.

2. System overview

2.1 Project configuration

SPI configuration:

SPI clock rate: 1 MHz

Transfer size: 8 bits per transfer

Clock phase (CPHA): '1' - Data is sampled on the second clock edge of the SCK.

Clock polarity (CPOL): '1' - SCK is active-low

LSB First (LSBF): '0' - SPI data is transferred MSB (bit 7) first.

UART Configuration:

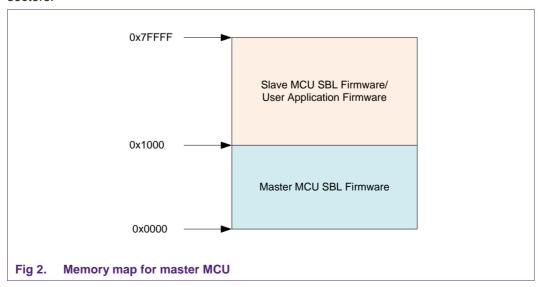
Baud rate: 115200

Data: 8 bits
Stop bits: 1
Parity bit: None
Flow Control: None

2.2 Memory map

2.2.1 Memory map for master MCU SBL

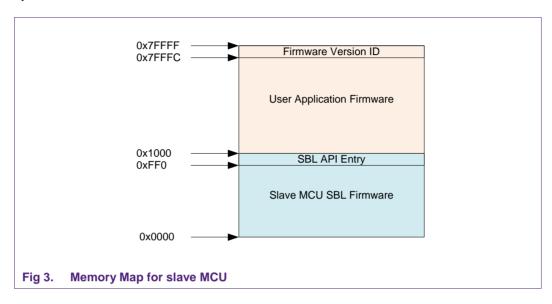
The master MCU's firmware resides on sector 0 of its flash memory. The remaining sectors are reserved to store firmware data. When master MCU has to upgrade slave MCU SBL firmware or User Application firmware in the slave, it will read data from these sectors.



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2.2.2 Memory map for slave MCU SBL

The flash memory is divided into two regions. One region is for the placement of the User Application Firmware and the other region is for the placement of Secondary Boot Loader. The SBL is placed at the first 4 kB of flash memory and runs first when the system resets.



As shown in Fig 3, the Firmware Version ID is stored in the last 4 bytes of flash memory; from 0x7FFC for LPC17xx MCU and 0x7FFC for LPC11xx MCU. The SBL also provides an entry point for calling SBL APIs. The address of the entry is from 0xFF0.

3. Functional description

3.1 SBL mode

3.1.1 Read firmware version ID

Function ID: 0x31

Description:

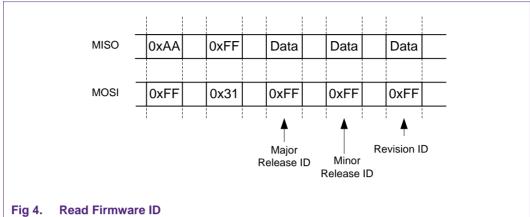
 This function allows the SBL master to read the firmware version ID of slave MCU SBL.

Implementation:

- The master MCU SBL waits for a READY byte (0xAA) over SPI.
- The master MCU SBL makes a request to read the firmware version ID by issuing a function ID (0x31) to the slave MCU SBL.
- Upon receiving the request, the slave MCU SBL will prepare the firmware version ID information.
- The master MCU SBL will then retrieve the firmware version ID information by issuing an SBL read instruction.

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SPI Communication Protocol:



Major release ID:

• Range of ID: 0 - 255

Minor release ID:

• Range of ID: 0 - 255

Revision ID:

• Range of ID: 0, a-f

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3.1.2 User application firmware upgrading

Function ID: 0x32

Description

• This function performs programming of the flash memory by the application program in a running system with an aim to upgrade the firmware.

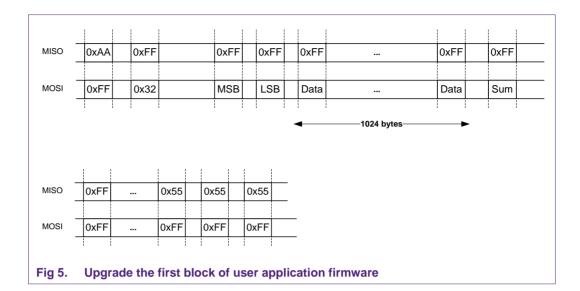
Implementation

- The master MCU SBL waits for a READY byte (0xAA) over SPI.
- The master MCU SBL makes a request to enter IAP mode by issuing a function ID (0x32) to the slave MCU SBL.
- The slave MCU SBL erases the last sector of Flash Memory, which stores the Firmware Version ID information. Then it enters to IAP mode.
- The master MCU SBL transfers firmware data to the slave MCU SBL one block at a time via SPI. Each block of data is 1 kB in size.
- The slave MCU SBL programs the flash one block at a time. The flash on the slave MCU SBL is divided into sectors. Each sector has a size of 4 kB. The slave MCU SBL will always prepare and erase the contents of the flash sector at the beginning of every new sector.
 - When the first block of data has been programmed, the slave MCU SBL is ready to receive the next block of data.
 - When the second block of data is received, since the contents of the entire flash sector have already cleared, the slave MCU SBL shall directly prepare and program the second block of data at a location that is 1 kB offset from the start of the sector.
- This process continues until the master MCU SBL sends the last block of flash data.
- In order to inform the slave MCU SBL that there are no more data, the master MCU SBL would send Block num (MSB) and Block num (LSB) bytes having a value of 0x00.
- When the IAP process is completed, the slave MCU SBL will execute Reset Handler of User Application at address 0x1004.

SBL communication protocol

1. The master MCU SBL follows this communication protocol to send the first 1 kB block of data.

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Function ID:

 The function ID used to perform IAP is 0x32. The master MCU SBL is required to send the function ID as the first byte so that the slave MCU SBL can enter IAP mode.

Block num (MSB & LSB)

Represents the block number that the master MCU SBL is sending.
 E.g. For block number 1: Block num (MSB) – 0x00, Block num (LSB) – 0x01
 For block number 257: Block num (MSB) – 0x01, Block num (LBD) – 0x01

1024 bytes of data

 Represents the 1 kB block of data that is used for programming the flash on the slave MCU SBL.

Checksum byte

- Checksum is used to check the integrity of the SBL transfer.
- · Checksum is initialized as 0.
- Computation of Checksum:

Checksum = 0 - Block num (MSB) - Block num (LSB) - Data_0 - ... - Data_1023

When the master MCU SBL completes the transmission of the block of data, the master MCU SBL will read continuously the status of the Secondary Boot Loader. When 3 bytes of 0x55 are received, the master MCU SBL understands that the slave MCU SBL has received data successfully. If not, the master MCU SBL will resend the block.

SBL Status

- If the three SBL status bytes received are '0x55', this means that programming is successful for the 1 kB of data.
- If the three SBL status bytes received are '0xFF', this means that there are errors during programming of the 1 kB of data.
- 2. The master MCU SBL follows this communication protocol to send the second and subsequent blocks of data.

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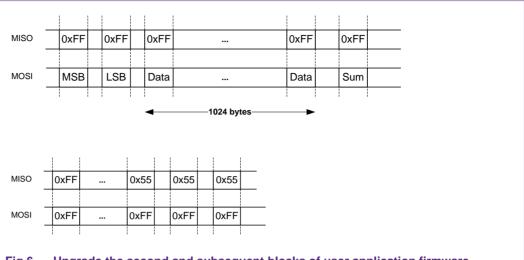


Fig 6. Upgrade the second and subsequent blocks of user application firmware

Fn ID

- The function ID is not required here, since the slave MCU SBL is now in IAP mode.
- The absence of function ID is the only difference in the SBL communication protocol between the transmission of the first and subsequent blocks of data.
- 3. The master MCU SBL follows this communication protocol to inform the slave MCU SBL that there are no more data to be sent from the master MCU SBL.

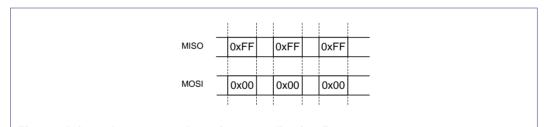


Fig 7. Inform that no more data of user application firmware

Block num (MSB) and (LSB)

Block num (MSB): 0x00Block num (LSB): 0x00

Checksum byte

- Generated using Command ID, Block num (MSB) and (LSB)
- Computation: Checksum = 0 Block num (MSB) Block num (LSB)

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3.1.3 SBL firmware upgrade

Function ID: 0x33

Description:

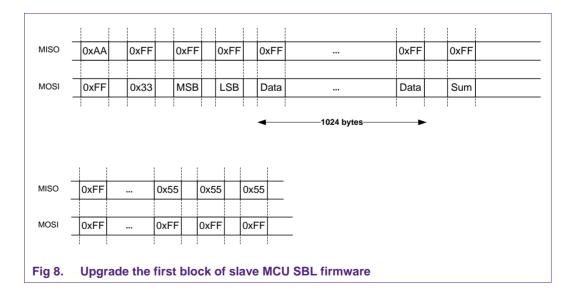
• This function performs programming of Sector 0 by the application program in a running system.

Implementation:

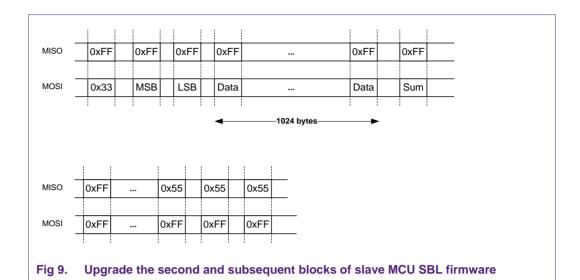
- The master MCU SBL waits for a READY byte (0xAA) over SPI.
- The master MCU SBL makes a request to program sector 0 of the flash memory by issuing a function ID (0x33) to the slave MCU SBL.
- Next, the master MCU SBL transfers firmware data to the slave MCU SBL one block at a time via SPI. Each block of data is 1 kB in size.
- The slave MCU SBL will always prepare and erase the contents of the flash sector at the beginning of every new sector.
- The slave MCU SBL programs the flash one block at a time (each sector of the flash memory contains four blocks of 1 kB of memory).
- After the master MCU SBL sends the last block of flash data, it would send Block Num (MSB) and Block Num (LSB) bytes having a value of 0x00 to inform the MCU that there are no more data.
- When the IAP process is completed, the slave MCU SBL will reset the system.

SBL communication protocol:

The SPI communication protocol for programming the SBL region on Flash Memory is similar to the SPI communication protocol for programming the User Application region.



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3.2 Fail-safe implementation

The fail-safe mechanism is to ensure that in the event of power loss during In-Application Programming, the MCU is able to re-start and complete the IAP process when the power comes back on.

Implementation:

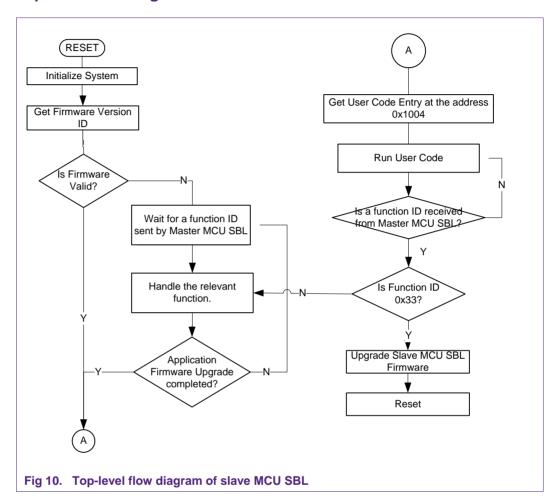
There are three important implementations in achieving the fail-safe mechanism for IAP.

- 1. Have a main function that decides if the flow of execution should go to the User Application or to the In-Application Programming Process.
- 2. Create and embed a Firmware ID at an address located at the end of the flash memory.
 - The Firmware ID is used as a determinant to identify if the User Application Code is intact. If the check is successful, it will enter the User Application. Otherwise, it enters IAP mode to program the User Application Code.
 - The Firmware ID is located at the end of the flash memory to ensure that this is the last data to be programmed during IAP process. In the event when the Firmware ID is invalid (0xFF), this means that the User Application Code has defects. One reason for this is that the previous IAP process is not successful.
 - In the main function, the MCU will always try to enter IAP mode if the Firmware ID is not valid.
- 3. The first task into the IAP mode is to erase the Firmware ID (the last sector to commence the IAP process).

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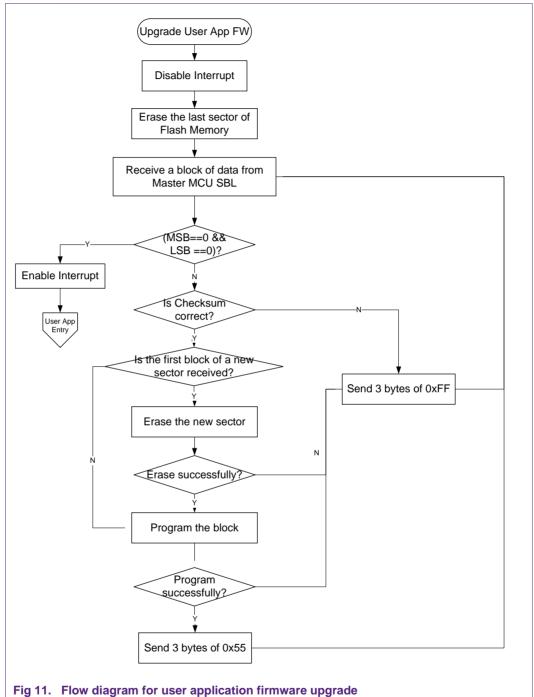
4. Implementation

4.1 Top-level flow diagram



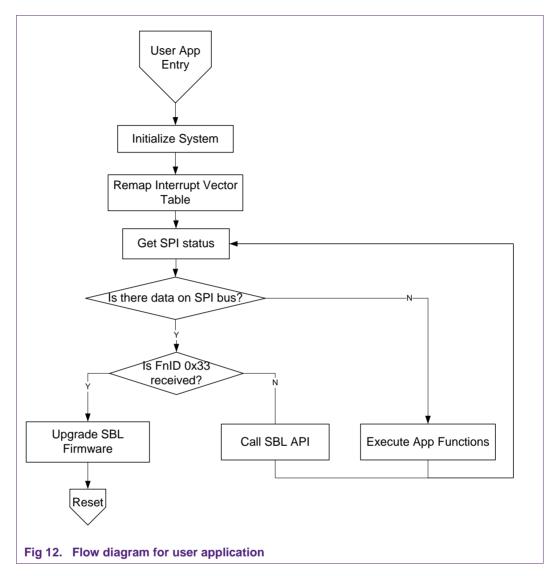
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4.2 SBL mode



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4.3 Application mode



The SBL function could be called in the following way using C.

```
#define SBL_LOCATION 0xFF1
typedef void (*sbl_api)(uint32_t API_Code, uint8_t* pParam);
```

Create function pointer and call it:

```
sbl_api entry;
entry = (sbl_api) (SBL_LOCATION);
(entry)(API_Code, Params);
```

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The parameters will be passed as shown in Table 1:

Table 1. SBL APIs

API_Code	Params	Description
0x01	None	Enter SBL Mode.
0x02	None	Exit SBL Mode.
0x03	Function ID	Handle command received over
	(Size = 1 byte)	SPI bus.

4.4 Scatter loading description file

To support In-Application Programming, a scatter loading description file is used to specify the memory map of the image to the linker, in order to control the grouping and placement of the image components.

This is important, because the new image is placed at its intended location and not any other location that can corrupt the codes used to perform IAP.

4.4.1 Scatter loading description file for SBL

The SBL resides on the first sector of the slave MCU. It is divided into two regions: one for storing the firmware itself, the other is used to public the SBL API for User Application.

Table 2. Scatter loading description file for SBL (LPC17xx)

Load Region	Execution Region	Input Sections
0x00000000 -	0x00000000 —	Interrupt Vector Table,
0x00000FEF	0x00000FEF	Code and RO data.
	0x10000000 – 0x10007BFF	RW data, ZI data.
	0x2007C000 - 0x20083FFF	RW data, ZI data.
0x00000FF0 - 0x00000FFF	0x00000FF0 - 0x00000FFF	SBL API.

Table 3. Scatter loading description file for SBL (LPC11xx)

Load Region	Execution Region	Input Sections
0x0000000 -	0x00000000 -	Interrupt Vector Table,
0x00000FEF	0x00000FEF	Code and RO data.
	0x10000000 -	RW data, ZI data.
	0x10001BFF	
0x00000FF0 -	0x00000FF0 -	SBL API.
0x00000FFF	0x00000FFF	

The last 1 kB of internal RAM, starting from 0x10007C00 for the LPC17xx and from 0x10001C00 for the LPC11xx, is used to store 1 kB of firmware data sent by the master MCU while upgrading firmware for the User Application.

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4.4.2 Scatter loading description file for user application

The User Application resides in flash memory, from sector 1 to the last sector of the slave MCU. It is also divided into 2 regions; 1 for storing firmware data itself and the other for storing Firmware Version ID.

Table 4. Scatter loading description file for user application (LPC17xx)

Load Region	Execution Region	Input Sections
0x00001000 -	0x00001000 -	Interrupt Vector Table,
0x0007FFFB	0x0007FFFB	Code and RO data.
	0x10000000 -	RW data, ZI data.
	0x10007BFF	
	0x2007C000 -	RW data, ZI data.
	0x20083FFF	
0x0007FFFC-	0x00000FF0 -	Firmware Version ID
0x0007FFFF	0x00000FFF	

Table 5. Scatter loading description file for user application (LPC11xx)

Load Region	Execution Region	Input Sections
0x00001000 -	0x00000000 —	Interrupt Vector Table,
0x00007FFB	0x00007FFB	Code and RO data.
	0x10000000 -	RW data, ZI data.
	0x10001BFF	
0x00007FFC-	0x00007FFC-	Firmware Version ID
0x00007FFF	0x00007FFF	

The last 1 kB of internal RAM is also used to store 1 kB firmware data sent by master MCU while upgrading firmware for SBL.

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5. How to run

This project is tested on Keil's MCB1700 with LPC1768 version 1 and Keil's MCB1000 with LPC1114. It requires two boards: one master and one slave.

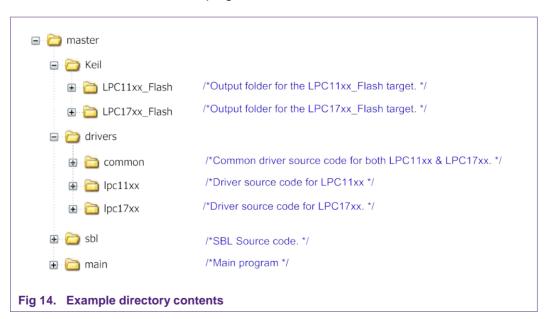
5.1 Directory contents

The folder structure of the project is described in Fig 13.



In each example folder, there are four sub-folders:

- Folder "Keil": includes Keil project file, scatter file and debug file. After compiling, output files are placed in a sub-folder of this folder. The name of the sub-folder is the same as the name of the selected target.
- Folder "drivers": includes source code for controlling peripherals including SPI, UART, and GPIO.
- Folder "sbl": includes SBL source code (Master/Slave role).
- Folder "main": includes main program.



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5.2 Hardware configuration

5.2.1 MCB1700

These jumpers must be configured as:

VDDIO: ONVDDREGS: ON

· Remaining jumpers: OFF

5.2.2 MCB1000

These jumpers must be configured as:

• J2 - VDD: ON

5.2.3 SPI connection

SPI pins:

Function	MCB1700	MCB1000
SCK	P0.15	P0.6
SSEL	P0.16	P0.2
MISO	P0.17	P0.8
MOSI	P0.18	P0.9

SPI connection:

- · SCK on master connects SCK on slave board
- SSEL on master connects to SSEL on slave board
- MISO on master connects to MISO on slave board
- · MOSI on master connects to MOSI on slave board

Common ground must be connected together between two boards.

5.3 Software configuration

5.3.1 Tera Term setting

Serial display configuration

- 115200 bps
- 8 data bit
- No parity
- 1 stop bit
- No flow control

5.4 Steps to run

Step 1: Open master MCU SBL Project in **SBL\Examples\master** folder.

- Select the target which relevant to the master board.
- Determine the size of User application firmware using SBL_FW_DATA_BLOCK_NUM macro in file "sbl.h".
- Build master MCU SBL Project.
- Burn hex file into master board. (If run on ROM mode)

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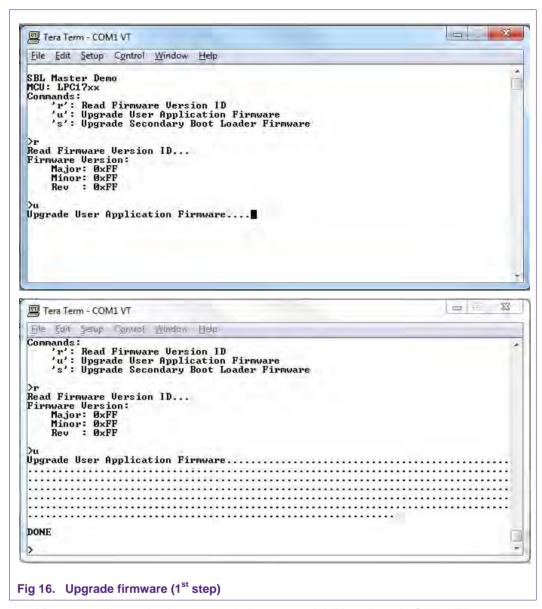
Step 2: Open slave MCU SBL Project in **SBL\Examples\slave** folder and User Application project in **SBL\Examples\user_app** folder.

- Select the target relevant to the slave board.
- Build the projects.
- · Erase all sectors on flash memory of slave board.
- Burn the hex file of slave MCU SBL Project into slave board.
- Burn the hex file of User Application project to master board.
- Step 3: Connect UART0 on master board to COM port on your computer.
- Step 4: Configure hardware, connect master board and slave board as above instruction.
- Step 5: Configure serial display as above instruction.
- Step 6: Reset Slave board. The LED at P2.2 is on to notify that the system is in SBL mode.
- Step 7: Reset the Master board. The welcome message is shown.

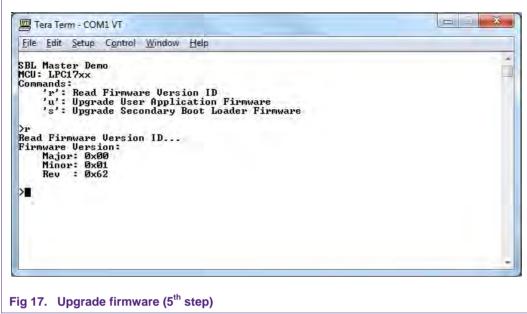


Fig 15. Terminal Output when Master board resets.

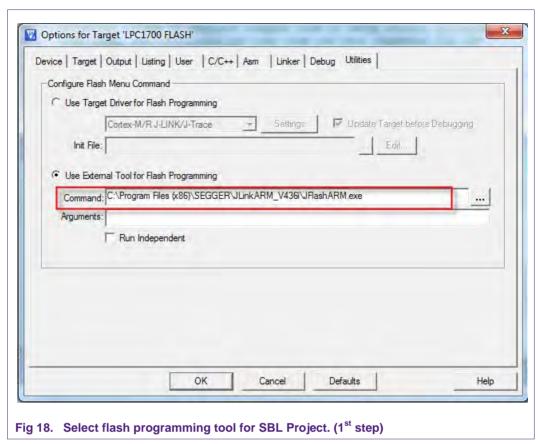
- Press 'r' to read the firmware version ID from slave. If this is the first time upgrading firmware, 0xFF will be displayed for all version details.
- Press 'u' to start upgrading firmware for slave. The master gets firmware data from sector 1 of its flash memory and is then sent to the slave. The size of firmware data is determined by the SBL_FW_DATA_BLOCK_NUM macro.



- After upgrading ends, the user code is executed. LED at P2.2 is OFF. LEDs at P2.3~P2.6 blink.
- Press 'r' to display version of the new firmware.

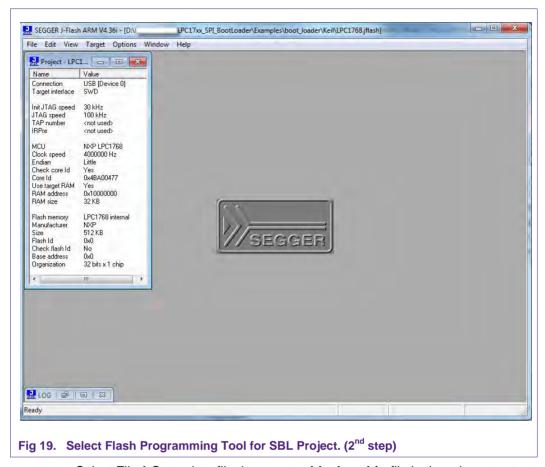


- To upgrade SBL firmware:
 - First, download the binary firmware file of the slave MCU SBL project (stored in the path SBL\Examples\slave\Keil\<Target Name>) to sector 1 of flash memory in master MCU:
 - Open slave MCU SBL Project.
 - Open Target Option Dialog, select Utilities Tab.
 - Choose External Tool for Flash Programming as below.

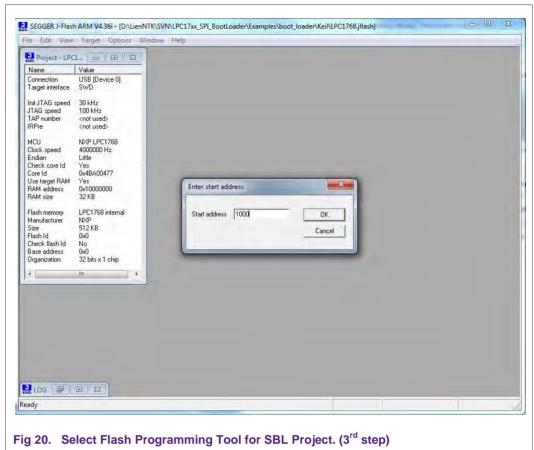


- Select Flash→ Download. The J-Flash ARM Application is opened.
- Select File → Open Project; browse to file "LPC1768.jflash" if the master is LPC17xx MCU. If it is LPC11xx MCU, please select "LPC1114.jflash".

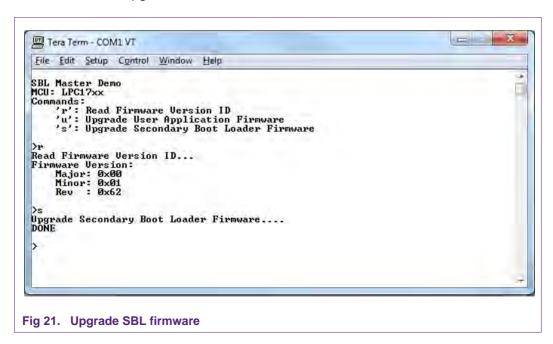
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- Select File→Open data file, browse to **sbl_slave.bin** file in the relevant output folder of SBL Project. Set the Start Address as 0x1000.



- Select Target→Program to program the master board.
 - Reset the master board.
- Press 's' to upgrade firmware for SBL.



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